DIODES



1N4448HWT

SURFACE MOUNT FAST SWITCHING DIODE

WWW.DZSC.

Features

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- Lead Free by Design/RoHS Compliant (Note 1)
- "Green" Device, Note 3 and 4

Mechanical Data

- Case: SOD-523
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Band
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish) annealed over Alloy 42 leadframe.
- Marking Code: T8
- Ordering Information: See Last Page
- Weight: 0.002 grams (approximate)

CATHODE MARK MARKING CODE ACH CATHODE MARK

SOD-523			
Dim	Min	Max	
Α	1.50	1.70	
В	1.10	1.30	
С	0.25	0.35	
D	0.70	0.90	
E	0.10	0.20	
G	0.55	0.65	
All Dimensions in mm			

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _R WM V _R	80 44 44 0	V
RMS Reverse Voltage	V _{R(RMS)}	57	V
Forward Continuous Current	I _{FM}	250	mA
Average Rectified Output Current	l ₀	125	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0s	I _{FSM}	2.0 1.0	А
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150	°C

Thermal Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	Pd	150	mW
Thermal Resistance Junction to Ambient (Note 2)	R ₀ JA	833	°C/W

Note: 1. No purposefully added lead.

- Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 3. Diode's Inc.'s "Green" Policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 4. Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

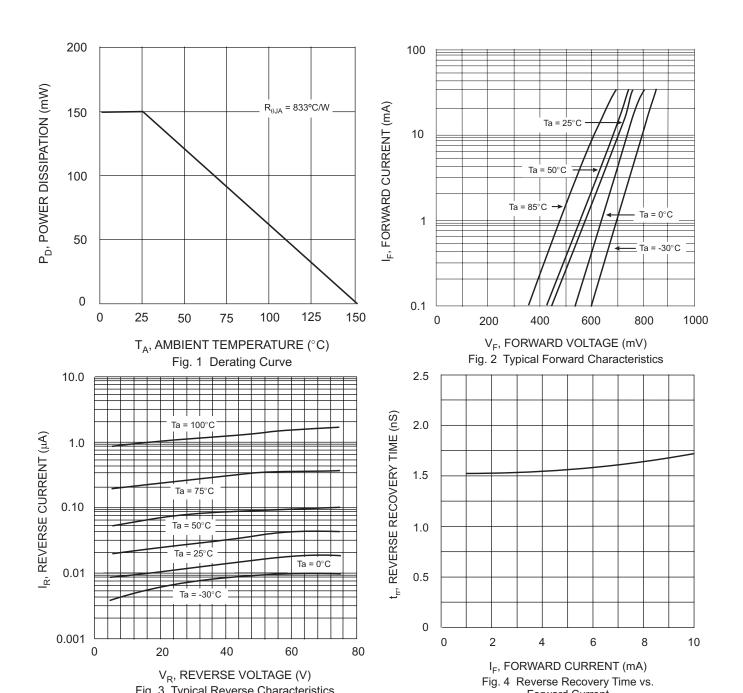




Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 5)	V _{(BR)R}	80	_	٧	I _R = 100μA
Forward Voltage	V _F	0.62 — — —	0.72 0.855 1.0 1.25	V	I _F = 5.0mA I _F = 10mA I _F = 100mA I _F = 150mA
Peak Reverse Current (Note 5)	I _R	_	100 50 30 25	nA μA μA nA	$V_R = 80V$ $V_R = 75V$, $T_j = 150$ °C $V_R = 25V$, $T_j = 150$ °C $V_R = 20V$
Total Capacitance	Ст	_	3.0	pF	V _R = 0.5V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	_	4.0	ns	$\begin{split} I_F &= I_R = 10 \text{mA}, \\ I_{rr} &= 0.1 \text{ x } I_R, \text{ R}_L = 100 \Omega \end{split}$

Note: 5. Short duration pulse test used to minimize self-heating effect.





Ordering Information (Note 6 & 7)

Device	Packaging	Shipping
1N4448HWT-7	SOD-523	3000/Tape & Reel

Note:

- 6. Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
- 7. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

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